TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

# Notification# 20190821000
# Datasheet for TLV702
# Information Only

**Date:** October 02, 2019
**To:** TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer’s defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

# Information Only
# Attachments

## Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

| DEVICE | CUSTOMER PART NUMBER |
|---|---|
| TLV70212DBVR | null |
| TLV70218DBVT | null |
| TLV70233DBVR | null |
| TLV70233DBVT | null |
| TLV70212DBVT | null |
| TLV70218DBVR | null |
| TLV70225DBVR | null |

Technical details of this Product Change follow on the next page(s).

| | | | |
|---|---|---|---|
| **PCN Number:** | 20190821000 | **PCN Date:** | Oct. 2, 2019 |
| **Title:** | Datasheet for TLV702 | | |
| **Customer Contact:** | PCN Manager | **Dept:** | Quality Services |

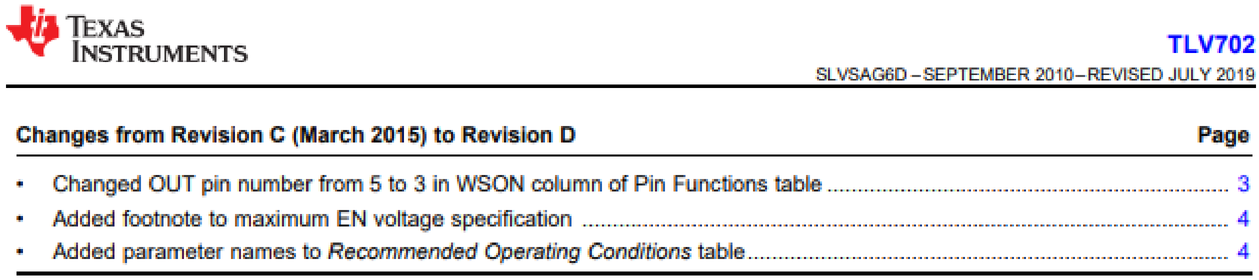
**Change Type:**

| | | | | | |
|---|---|---|---|---|---|
| ☐ | Assembly Site | ☐ | Design | ☐ | Wafer Bump Site |
| ☐ | Assembly Process | ☒ | Data Sheet | ☐ | Wafer Bump Material |
| ☐ | Assembly Materials | ☐ | Part number change | ☐ | Wafer Bump Process |
| ☐ | Mechanical Specification | ☐ | Test Site | ☐ | Wafer Fab Site |
| ☐ | Packing/Shipping/Labeling | ☐ | Test Process | ☐ | Wafer Fab Materials |
| | | | | ☐ | Wafer Fab Process |

## Notification Details

### Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



TEXAS INSTRUMENTS

TLV702

SLVSAG6D – SEPTEMBER 2010 – REVISED JULY 2019

**Changes from Revision C (March 2015) to Revision D** — **Page**

- Changed OUT pin number from 5 to 3 in WSON column of Pin Functions table ........ 3
- Added footnote to maximum EN voltage specification ........ 4
- Added parameter names to *Recommended Operating Conditions* table ........ 4

The datasheet number will be changing.

| Device Family | Change From: | Change To: |
|---|---|---|
| TLV702 | SLVSAG6C | SLVSAG6D |

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TLV702

### Reason for Change:

To accurately reflect device characteristics.

### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

### Changes to product identification resulting from this PCN:

None.

### Product Affected:

| | | | |
|---|---|---|---|
| TLV70212DBVR | TLV70228DSER | TLV70230DBVT | TLV70236DSER |
| TLV70212DBVT | TLV70228DSET | TLV70231DBVR | TLV70236DSET |
| TLV70215DBVR | TLV70228PDBVR | TLV70231DBVT | TLV70237DBVR |
| TLV70215DBVT | TLV70228PDBVT | TLV70233DBVR | TLV70237DBVT |
| TLV70218DBVR | TLV70229DBVR | TLV70233DBVT | TLV70237DSER |
| TLV70218DBVT | TLV70229DBVT | TLV70233DSER | TLV70237DSET |
| TLV70225DBVR | TLV70229DSER | TLV70233DSET | TLV70245DBVR |
| TLV70225DBVT | TLV70229DSET | TLV70235DBVR | TLV70245DBVT |
| TLV70225DSER | TLV70230DBVR | TLV70235DBVT | TLV702475DBVR |
| TLV70225DSET | TLV702475DBVT | | |

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

| **Location** | **E-Mail** |
|---|---|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| WW PCN Team | PCN_ww_admin_team@list.ti.com |

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